The production and test of frond-end electronics board (GEB) for CMS-GEM GE1/1 project in China

Wei Shan, Shaokun He, Geng Chen,
Yong Ban, Dayong Wang
Peking University
2016.12.17



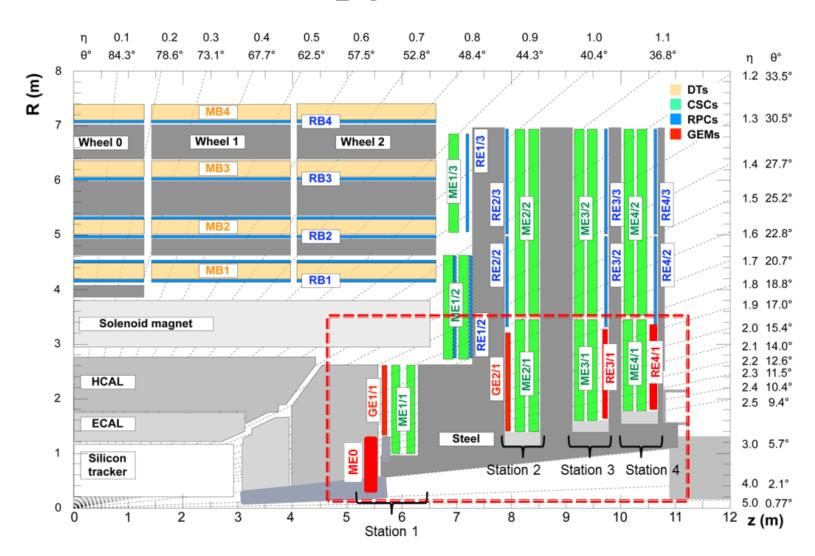


Outline

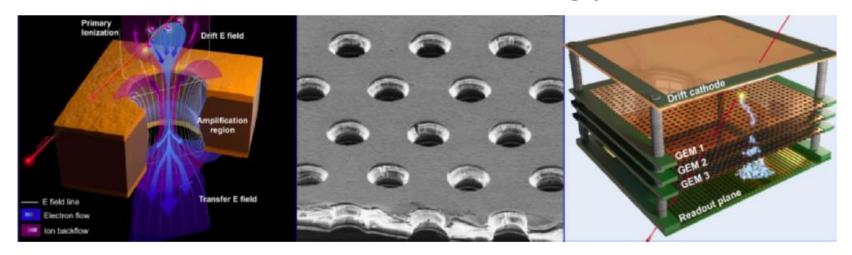
- Introduction
- > CMS GE1/1
- GEM Detector technology
- ➤ GE1/1 Electronics System
- □FPGA board for GEB test
- Connectivity Test
- Production & Test Results
- ■Summary & Outlook

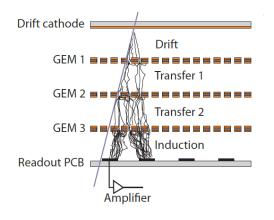
Introduction

Muon GEM upgrade: GE1/1



GEM Detector technology

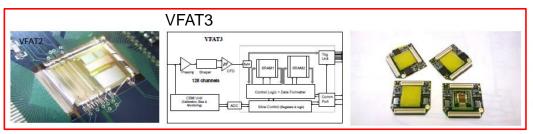




- □ Single-Mask GEM Fabrication Technology
- ☐ Simple Assembly
- ☐ Eco friendly Gas mixture-Ar/CO₂ 70:30
- □ Performance Requirements commensurate with upgrade station

GE1/1 Electronics System

GE1/1 Electronics System



VFAT3 front-end ASIC development

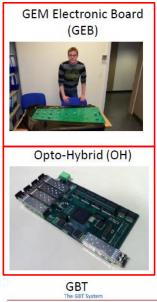
P. Aspell G. De Lentdecker

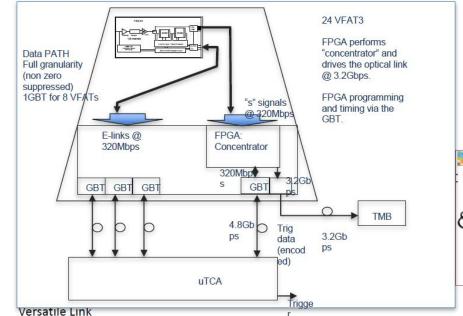
F. Loddo.

G. De Robertis

& Team

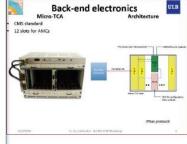
MP7 / CTP7







μTCA AMC13, MCH

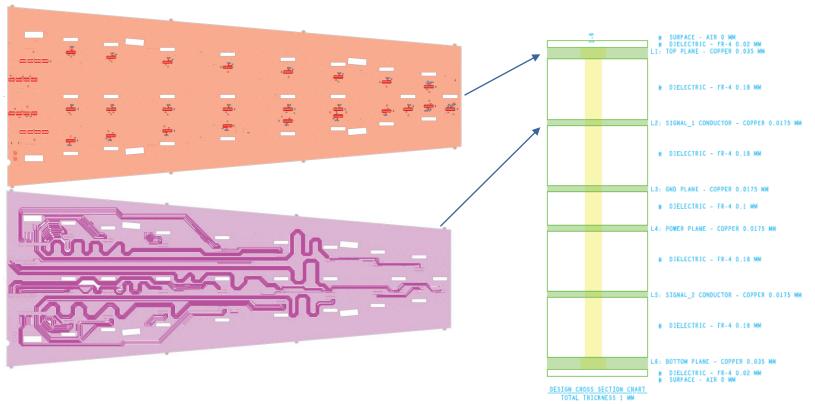


Use of many common developments such as GBT,

Versatile Link, μTCA backend

The control, readout and power to/from the VFAT3 hybrid are delivered via electrical signals (E-links) running through the GEB to the opto-hybrid.

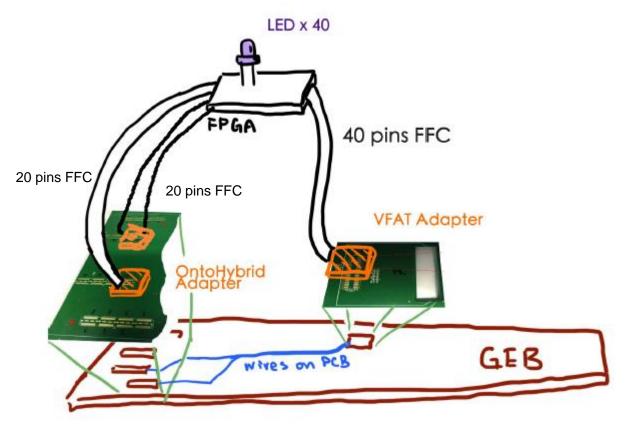
GEB (GEM Electronic Board)



- GEB is fabricated as a single large multilayer PCB, lines on the board are intensive.
- The GEBs were designed by LUT(in Finland) and CERN.
- The GEBs were manufactured in Shenzhen.
- The connectivity of the GEBs was tested both by the factory and our PKU group.

FPGA board for GEB test

The design concept of FPGA for GEB test



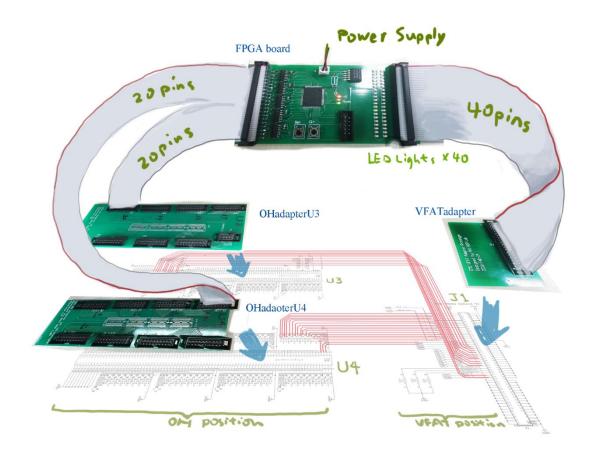
Check the connectivity between VFAT connector and OptoHybrid connector in the GEB

Core function board(FPGA-based) for GEB test

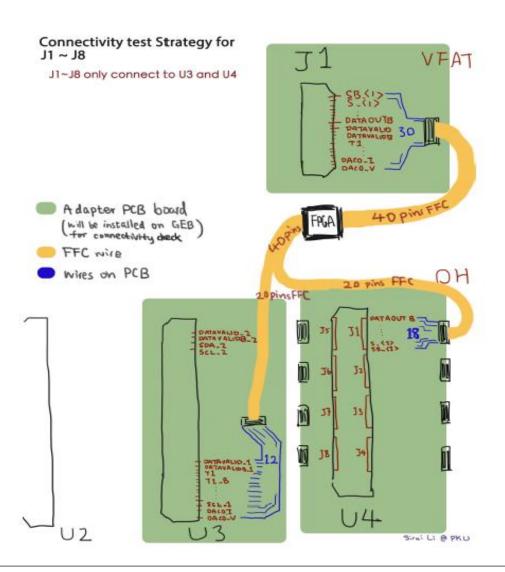


GEB testing utility

- FPGA Board
- VFAT Adapter
- OptoHybrid Adapter
- FFC wire

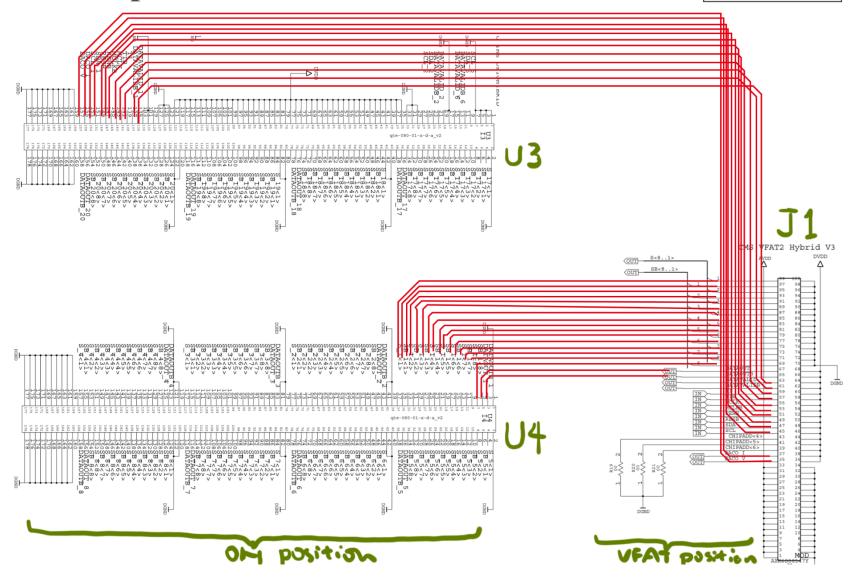


Connectivity test Strategy

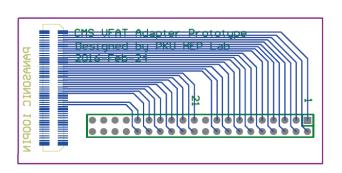


Connection Between one VFAT position and OH position on GEB





VFAT Adapter/ OH Adapter PCB

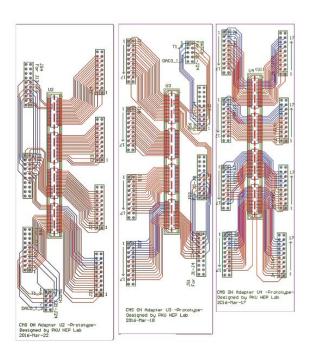


Back side

VFAT Adapter

Front side

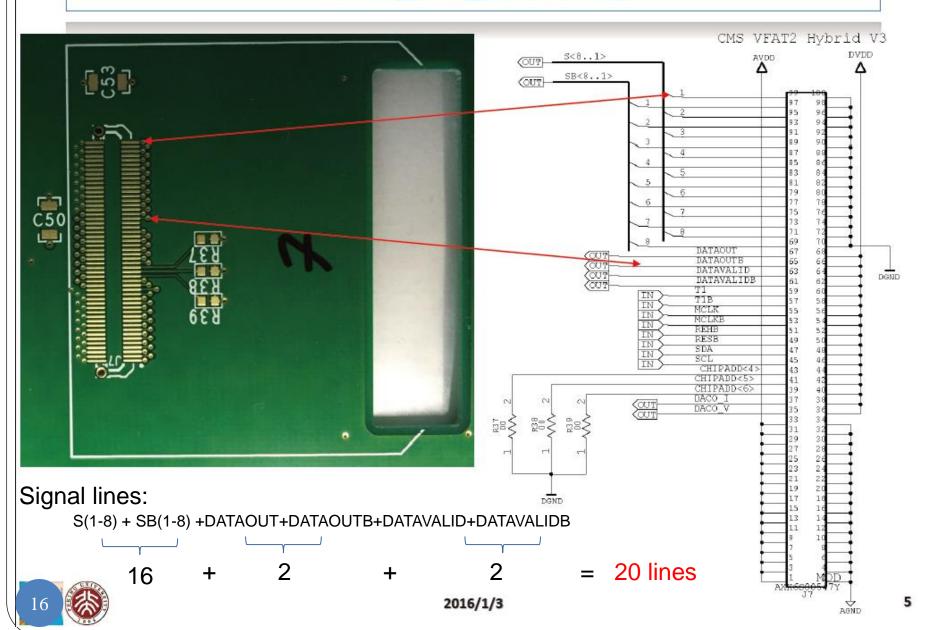




OH Adapter



GEB_V2_L VFATs



Optohybrid region



Mapping from VFAT to OptoHybrid

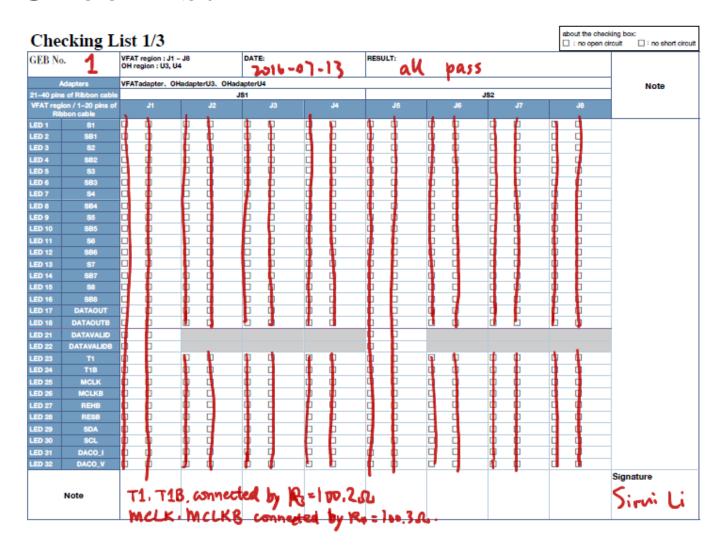
Strips on Hybrid	Strips on OptoHybrid region(U2, U3) Corresponding to different VFATs 12/30 lines tested														
(VFAT) Region	1 - 4	5 - 8	9 - 12	13 - 16	17 - 20	21 - 24									
T1, T1B	T1,	T1B	T1_2,	T1B_2	T1_3, T1B_3										
MCLK, MCLKB	MCLK,	MCLKB	MCLK_2,	MCLKB_2	MCLK_3, MCLKB_3										
REHB, RESB	REHB,	RESB	REHB_2	, RESB_2	REHB_3, RESB_3										
SDA, SCL	SDA_1, SCL_1	SDA_2, SCL_2	SDA_3, SCL_3	SDA_4, SCL_4	SDA_5, SCL_5	SDA_6, SCL_6									
DACO_I, DACO_V	DACO_I,	DACO_V	DACO_I_2,	DACO_V_2	DACO_I_3, DACO_V_3										

Only VFAT 1, 5, 9, 13, 17, 21 have the strips for DATAVALID, DATAVALIDB; corresponding to OptoHybrid region *_1, *_2, *_3, *_4, *_5, *_6, respectively.



^{*} Stands for DATAVALID and DATAVALIDB.

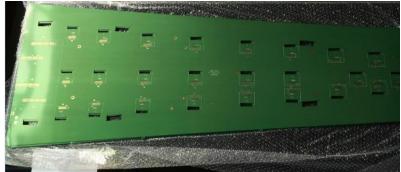
Checklist



GEB test at CERN







Production & test results

Time	GEBs	Total yields	Finished product	Yield rate
Apirl,2016 July,2016	Long GEB	40	8	20%
Oct,2016	Short GEB	40	10	25%

- ➤ Taking into account Mr. Xue(an engineer in PKU HEP group)'s comments, the design for the short GEB is slightly changed and the yield rates for the short GEBs are improved.
- ➤ From the final test results at CERN, 7 long GEBs and 9 short GEBs work very well, the others are found to have some short circuits.

 All those boards are taken as the prototypes and meet requirements of the Slice Test at CERN.

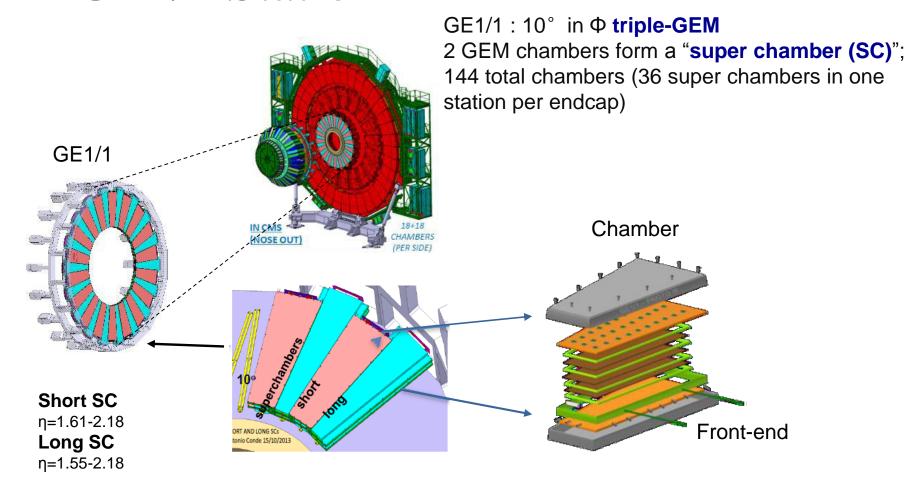
Summary & Outlook

- 8 Long GEBs and 10 short GEBs were manufactured in Shenzhen.
- The FPGA-based test boards were developed by PKU HEP group independently. It worked well for the test of the connectivity of the GEBs.
- The test for GEBs went very well both in China and at CERN.
- 7 long GEBs and 9 short GEBs work very well, All of them meet requirements of the Slice Test.
- □ Final version of the GEBs will be done in 2017.

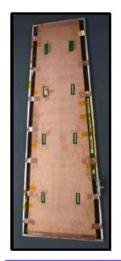
Thank you!

Back up

GE1/1 Station



Chambers













2010

2011

2012

2013

2014

2015

R&D phase

Toward production phase

TDR

GE1/1-I

- -> first 1m-class GEM detector ever built
- -> single-mask technology
- -> 99x(22-45) cm²
- -> 1024 readout
- -> gap config. 3/2/2/2
- -> use of spacer grid and glue

GE1/1-II

- -> Optimization of the electric field configuration
- -> single-mask technology
- -> 99x(22-45) cm2
- -> 3072 readout channels
- -> gap config. 3/1/2/1
- -> use of spacer grid and glue

GE1/1-III

- -> first use of the selfstretching technique
- -> single-mask technology
- -> 99x(22-45) cm²
- -> 3072 readout
- -> gap config. 3/1/2/1
- -> No spacers but glue on the external frame

GE1/1-IV

- -> Optimization of the mechanics and assembly
- -> single-mask technology
- -> 99x(22-45) cm2
- -> 3072 readout channels
- -> gap config. 3/1/2/1
- -> No glue/no spacers

GE1/1-V

- -> Optimization of the mechanics
- -> stretching apparatus inside the gas volume
- -> single-mask technology
- -> 99x(22-45) cm²
- -> 3072 readout
- -> gap config. 3/1/2/1
- -> No glue/no spacers

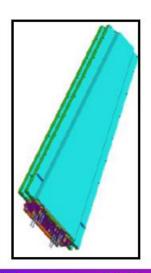
GE1/1-VI

- -> Optimization of the mechanics
- -> single-mask technology
- -> design for long and short detectors
- -> 99x(22-45) cm²
- -> 120x(20-50) cm²
- -> 3072 readout channels (new mapping)
- -> gap config. 3/1/2/1
- -> No glue/no spacers

Super Chambers









2016

2017

2018

2019

2020

Slice test installation

Production phase & installation

GE1/1-VII (slice test)

- -> Optimization of the mechanics
- -> Optimization of the grounding Optimization of the HV distribution
- -> single-mask technology
- -> 99x(22-45) cm2
- -> 120x(20-50) cm²
- -> 3072 readout channels
- -> gap config. 3/1/2/1
- -> No glue/no spacers

- -> External (w.r.t . CERN) production sites certification and chamber components shipment
- -> GE1/1 chamber assembly and certification
- -> Super chamber mechanics optimization
- -> First test with final front-end electronics

GE1/1-VIII (LS2)

- -> GE1/1 super chamber assembly and certification with final front-end
- electronics -> First batch of
- Superchamber shipped to P5

- GE1/1 super chambers ready in P5 for installation
- Installation and cabling of all super chambers
- Commissioning in situ with cosmic muons
- Super chamber characterization in situ with cosmic muon
- First data with LHC beam

GEB PCB inspection & testing

- ➤ Visual check
- >AOI(Automated optical inspection)
- >Flying probe
- >FPGA based test

AOI

AOI(Automated optical inspection) Bare PCB inspection

Line width violations.



Spacing violation.



Excess copper.



Shorts circuits



Cuts



- Hole breakage a drilled hole (via) is outside of its landing pad.
- wrong mounting components identified







Flying Probe Test



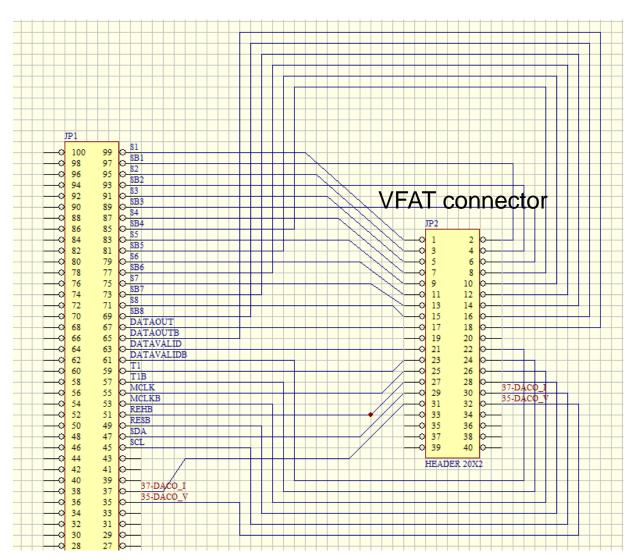




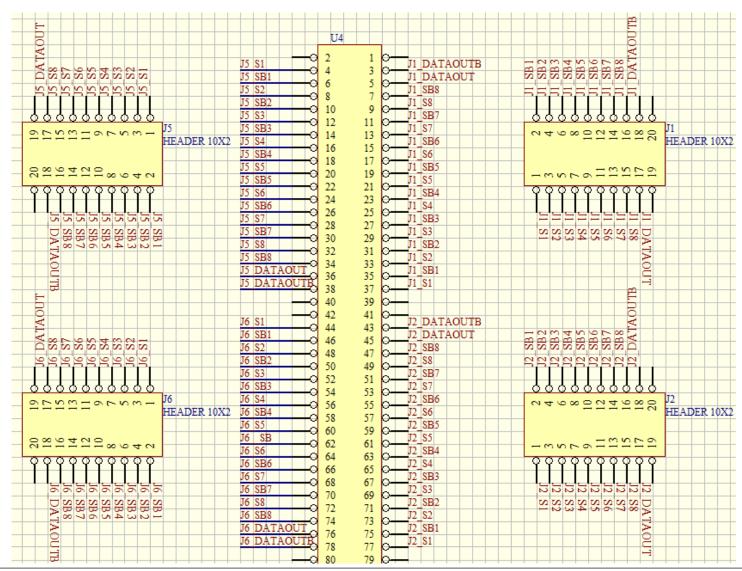
Flying Probe

Specification	SURPASS X1200
Test method	Resistance, phase deviation
Min. test area	76X76mm
No. of Flying Probe	2 front, 2 rear
No. of CCD Camera	2 front, 2 rear
Positional accuracy	±5µm
Resolution	2μm
Max. Test area	1200x700mm
Board Thickness	0.3-13mm
Min. Pad pitch	150µm
Min. Pad size	75µm

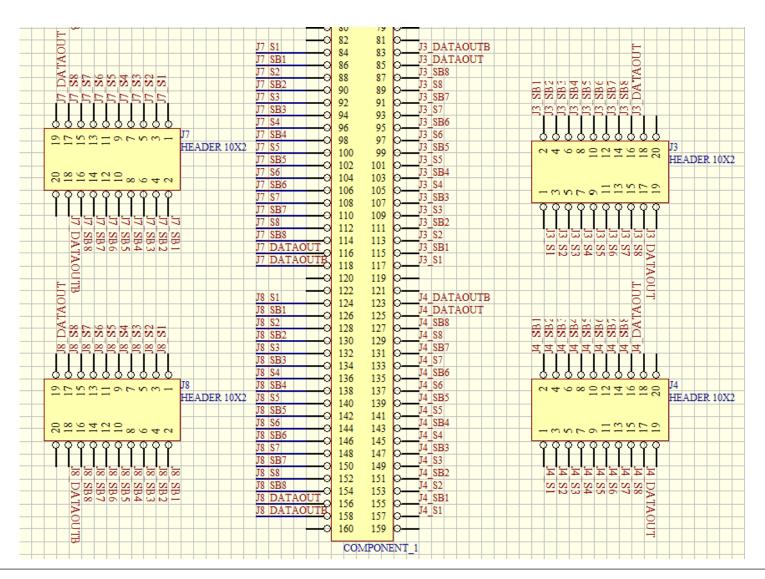
VFAT Adapter Scheme



OHAdapter Scheme



OHAdapter Scheme



Checklist 1/3

Che	cking L	ist 1	1/3											bout the chec : no open o	e checking box: open circuit : no short circui		
GEB No).	VFAT region : J1 ~ J8 DATE: OH region : U3, U4								RES	JLT:						
-	dapters	VFATac	dapter, OH	fadapt	terU3、OH	adapterl	J4						Note				
21~40 pin	s of Ribbon cable					J\$1				1							
	ion / 1~20 pins of bon cable		Ji		J2		J3		J4		J5	J6	J7		J8		
ED 1	\$1																
ED 2	SB1																
ED 3	82																
ED 4	SB2																
ED 5	\$3																
ED 6	SB3																
ED 7	S4																
ED 8	SB4																
ED 9	\$5																
ED 10	SB5																
ID 11	\$6																
ID 12	SB6																
ED 13	S7																
D 14	SB7																
ED 15	S8																
ED 16	SB8																
ED 17	DATAOUT																
ED 18	DATAOUTB																
ED 21	DATAVALID																
ED 22	DATAVALIDB																
ED 23	TH																
ED 24	T1B																
ED 25	MCLK																
ED 26	MCLKB																
ED 27	REHB																
ED 28	RESB																
ED 29	SDA															1	
ED 30	SCL															Ť	
ED 31	DACO_I															†	
ED 32	DACO_V															İ	
	Note															Signature	

Checklist 2/3

Checking List 2/3 Attention: OHadapterU4 is to be connected with U1 region on GEB

GEB No).		region : J9 - egion : U1, U			DATI	Ē:		RESU	JLT:							
	Adapters	VFAT	adapter, Ol	ladapt	erU4. OHac	lapterl	12										Note
	s of Ribbon cable					1\$3							J\$4				
VFAT reg	ion / 1~20 pins of		J9		J10		J11	J12		J13		J14		J15		J16	
LED 1	S1																
LED 2	SB1																Ť
LED 3	\$2																I
LED 4	SB2																
LED 5	\$3																
LED 6	SB3																
LED 7	S4																1
LED 8	SB4																1
LED 9	\$5																
LED 10	SB5																
LED 11	S6																
LED 12	SB6																
LED 13	S7																
LED 14	SB7																
LED 15	S8																
LED 16 LED 17	SB8 DATAOUT																
LED 17	DATAOUTB																
LED 18	DATAVALID		0					 	-								
LED 21	DATAVALIDB																-
LED 23	T1																
LED 24	TIB				0		0		6				0	0	0		
LED 25	MCLK												0				
LED 26	MCLKB				0		0					0	0	0	0		+
LED 27	REHB			0	<u> </u>		0	 -			0	<u> </u>	0	<u> </u>			†
LED 28	RESB																†
LED 29	SDA				0		0					0		0			†
LED 30	SCL				0		0					0					†
LED 31	DACO_I																†
LED 32	DACO_V																†
	Note								•		·		·				Signature:

Checklist 3/3

Checking List 3/3 Attention: There is a connecter (SWTCH) on both OHadpterU2 and OHadapterU3. They should be connected using 10 pins cable beforehand.

										D.E.O.					
GEB No			region : J1 egion : U2, U			DATI	E			RES	ULT:				
	dapters	VFATadapter、OHadapterU2、OHadapterU3										Note			
l~40 pins	s of Ribbon cable					J\$5									
FAT regi Rib	on / 1~20 pins of bon cable		J17		J18		J19		J20		J21	J22	J23	J24	
ED 1	S1														
D 2	SB1														
ID 3	\$2														
ID 4	SB2														
D 6	\$3														
ID 6	SB3														_
D 7	S4														_
ID 8	SB4														_
ED 9	\$5														_
ED 10	SB5														_
ED 11	S6														_
D 12	SB6														
D 13	S7														
ID 14	SB7														
D 15	S8														
ID 16	SB8														
ED 17	DATAOUT														
D 18	DATAOUTB														
ED 21	DATAVALID														
ED 22	DATAVALIDB														
ED 23	TH														_
ED 24	T1B														_
ED 25	MCLK														_
ED 26	MCLKB														_
ED 27	REHB														_
ED 28	RESB														_
ID 29	SDA														_
ED 30	SCL						-								_
ED 31	DACO_I														_
ED 32	DACO_V														Cianatura
	Note														Signature: